

# IEEE Wireless and Microwave Technology Conference

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## Local Industry Liaison

TBD

## IEEE YP Liaison

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## WAMICON EXCOM Chair

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**WAMICON 2018**  
April 9<sup>th</sup> and 10<sup>th</sup> 2018  
Sheraton  
Sand Key, Florida

## Submission Deadline: Friday February 9, 2018

The 19th annual IEEE Wireless and Microwave Technology Conference (WAMICON 2018) will be held in Clearwater, Florida on April 9<sup>th</sup> and 10<sup>th</sup> 2018. The conference will address up-to-date multidisciplinary research needs and interdisciplinary aspects of wireless and RF technology. The program includes both oral and poster presentations as well as tutorials and special sessions. Prospective authors are invited to submit original and high-quality work for presentation at WAMICON 2018 and publication in IEEE Xplore. Conference website is [www.wamicon.org](http://www.wamicon.org). **WAMICON welcomes and encourages strong participation from industry, academic and governmental groups interested in advancing wireless and microwave technology.**

## TOPICS OF INTEREST INCLUDE

The central theme of WAMICON2018 will be “**mm-Waves and Internet of Things (IoT) for Commercial and Defense**”. We welcome submissions on all aspects of mm-wave and IoT related technologies including antennas, passive and active circuits, communication theory, and system concepts.

### mm-Wave and Internet of Things (IoT)

5G Communications, MIMO and massive MIMO, beamforming, Machine-to-Machine (M2M) wireless, Internet of Space, Ultra-Wideband (UWB), Multi-Carrier, Spread Spectrum, Channel Characterization and Modeling, Cognitive Radios and Software Defined Radios

### Power Amplifiers

High-Efficiency PAs, Linearization and Efficiency Enhancement Techniques and Topologies, Novel PA Architectures, High-Power Devices, Linear and Nonlinear Device Modeling and CAD, Thermal Considerations and Reliabilities, PA Applications

### Active Components and Systems

Transceiver Design, Multi-Band RF Circuits and Systems, System-On-Chip, System-In-Package, Low-Power IC, Low-Noise IC, Radar RF/MMIC Electronics, Terahertz Electronics, Active (Non-Foster) Filters and Non-Foster Impedance Matching

### Passive Components and Antennas

Filters, Transmission Line Components, MEMS, Advanced Packaging, Antennas and Arrays, Meta-Materials, Frequency Selective Surface, Non-Foster Impedance Matching

### Microwave Applications

Biomedical Applications, Wireless Sensing, Energy Harvesting, Wireless Power Transfer, Radar, Additive Manufacturing

## PAPER SUBMISSION INSTRUCTIONS

Authors are asked to submit papers electronically in .PDF format. In order to be considered for publication by the Technical Program Committee, a submission of 3-4 pages, clearly describing the concept and results must be submitted before the deadline of February 9, 2018. The conference webpage at [www.wamicon.org](http://www.wamicon.org) has complete details of submission requirements. Submissions will be evaluated for originality, significance of the work, technical soundness, and interest to a wide audience.



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**Papers Due: Fri., Feb. 9, 2018**  
**Author Notification: Fri., Feb. 23, 2018**  
**Final Papers Due: Fri., Mar. 2, 2018**